

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SURFACE MOUNT SWITCHING DIODE ARRAY

Features

- Fast Switching Speed
- High Reverse Breakdown Voltage
- Low Leakage Current
- Low Capacitance
- Two "BAV99" Circuits In One Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (BAV99HDWQ)

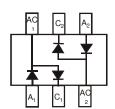
Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe; (Lead-Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

SOT363



Top View



Top View Internal Schematic

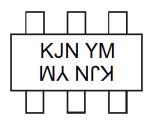
Ordering Information (Notes 4)

Part Number	Qualification	Case	Packaging
BAV99HDW-13	AEC-Q101	SOT363	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>
 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



KJN = Product Type Marking Code YM = Date Code Marking Y = Year (ex: C = 2015)M = Month (ex: 9 = September)

Date Code Key

Year	2015		2016	2017		2018	2019		2020	2021		2022
Code	С		D	Е		F	G		Н			J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	100	V
RMS Reverse Voltage	$V_{R(RMS)}$	71	V	
Forward Continuous Current (Note 5)	I _{FM}	200	mA	
Repetitive Peak Forward Current		I _{FRM}	500	mA
	@ t = 1.0μs		4	
Non-Repetitive Peak Forward Surge Current	@ t = 1.0ms	I _{FSM}	1.0	Α
	@ t = 1.0s		0.5	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{\theta JA}$	500	°C/W
Thermal Resistance Junction to Solder Point (Note 6)	$R_{ heta JSP}$	260	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

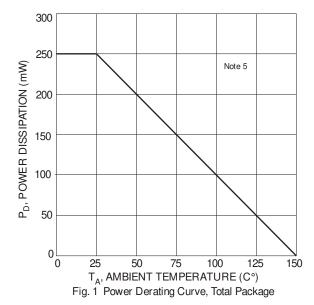
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	100	_	V	$I_R = 2.5\mu A$
		_	0.715	V	$I_F = 1.0 \text{mA}$
Forward Voltage	VF	_	0.855		$I_F = 10mA$
o waru voitage	VF	_	1.0		$I_F = 50 \text{mA}$
		_	1.25		$I_F = 150 \text{mA}$
		_	0.5	μΑ	$V_R = 80V$
Reverse Current (Note 7)		_	50		$V_R = 80V, T_J = +150$ °C
Heverse Guiterit (Note 7)	I _R	_	30		$V_R = 25V, T_J = +150$ °C
		_	30	nA	$V_R = 25V$
Total Capacitance	C _T	_	1.5	рF	$V_R = 0, f = 1.0MHz$
Reverse Recovery Time	+	_	4.0	ns	$I_F = I_R = 10 \text{mA},$
neverse necovery fillie	t _{RR}				$I_{RR}=0.1~x~I_R,~R_L=100\Omega$
Forward Recovery Voltage	V_{FR}	_	1.75	V	$IF = 10 \text{ mA}; t_R = 20 \text{ns}$

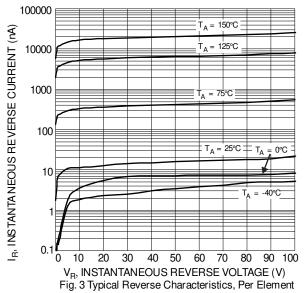
Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.

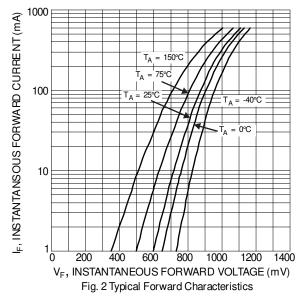
^{6.} Soldering points at pins AC₁, AC₂ and C₁, C₂.

^{7.} Short duration pulse test used to minimize self-heating effect.









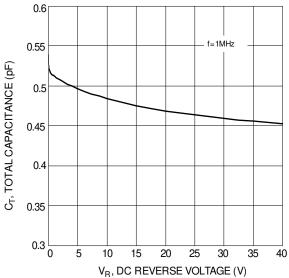


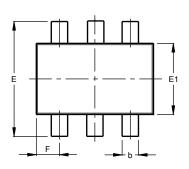
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

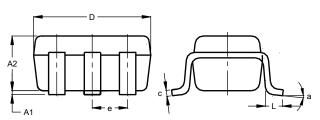


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



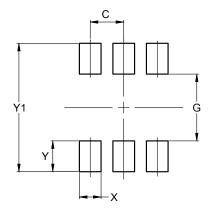


SOT363					
Dim	Min	Max	Тур		
A1	0.00	0.10	0.05		
A2	0.90	1.00	1.00		
b	0.10	0.30	0.25		
С	0.10	0.22	0.11		
D	1.80	2.20	2.15		
Е	2.00	2.20	2.10		
E1	1.15	1.35	1.30		
е	0.650 BSC				
F	0.40	0.45	0.425		
L	0.25	0.40	0.30		
а	0°	8°	_		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



Dimensions	Value		
Dimensions	(in mm)		
С	0.650		
G	1.300		
Х	0.420		
Υ	0.600		
Y1	2.500		



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